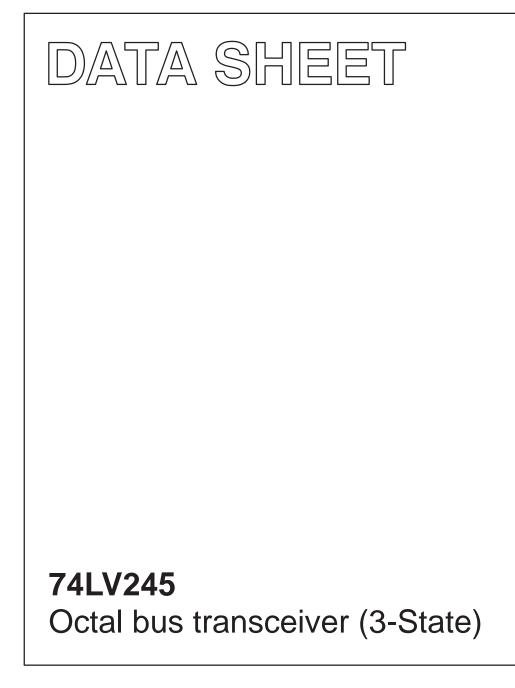
# INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Feb 19 IC24 Data Handbook

1998 Apr 20



HILIP

Philips Semiconductors

74LV245

#### **FEATURES**

- Wide operating voltage: 1.0 to 5.5 V
- Optimized for low voltage applications: 1.0 to 3.6 V
- Accepts TTL input levels between V<sub>CC</sub> = 2.7 V and V<sub>CC</sub> = 3.6 V
- Typical V<sub>OLP</sub> (output ground bounce) < 0.8 V at V<sub>CC</sub> = 3.3 V,  $T_{amb} = 25^{\circ}C$
- Typical V<sub>OHV</sub> (output V<sub>OH</sub> undershoot) > 2 V at V<sub>CC</sub> = 3.3 V,  $T_{amb} = 25^{\circ}C$
- Output capability: bus driver
- I<sub>CC</sub> category: MSI

### QUICK REFERENCE DATA

GND = 0 V;  $T_{amb} = 25^{\circ}C$ ;  $t_r = t_f \le 2.5$  ns

#### DESCRIPTION

The 74LV245 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT245.

The 74LV245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The 74LV245 features an output enable (OE) input for easy cascading and a send/receive (DIR) input for direction control. OE controls the outputs so that the buses are effectively isolated.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay $A_n$ to $B_n$ ; $B_n$ to $A_n$	$C_L = 15 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	7.0	ns
Cl	Input capacitance		3.5	pF
C <sub>I/O</sub>	Input/output capacitance		10	pF
C <sub>PD</sub> Power dissipation capacitance per buffer		$V_{CC} = 3.3 V$ $V_{I} = GND$ to $V_{CC}$ , note 1	40	pF

NOTE:

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:

 $f_i = \text{input frequency in MHz; } C_L = \text{output load capacitance in pF;} \\ f_o = \text{output frequency in MHz; } V_{CC} = \text{supply voltage in V;}$ 

 $\sum (C_L \times V_{CC}^2 \times f_0)$  = sum of the outputs.

#### ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic DIL	–40°C to +125°C	74LV245 N	74LV245 N	SOT146-1
20-Pin Plastic SO	–40°C to +125°C	74LV245 D	74LV245 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +125°C	74LV245 DB	74LV245 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV245 PW	74LV245PW DH	SOT360-1

#### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	FUNCTION
1	DIR	Direction
2, 3, 4, 5, 6, 7, 8, 9	$A_0$ to $A_7$	Data inputs/outputs
10	GND	Ground (0 V)
18, 17, 16, 15, 14, 13, 12, 11	B <sub>0</sub> to B <sub>7</sub>	Data inputs/outputs
19	ŌĒ	Output enable input (active LOW)
20	V <sub>CC</sub>	Positive supply voltage

### **FUNCTION TABLE**

INPU	JTS	INPUTS/OUTPUT				
OE	DIR	A <sub>n</sub>	B <sub>n</sub>			
L	L	A = B	Inputs			
L	Н	Inputs	B = A			
Н	X	Z	Z			

NOTES:

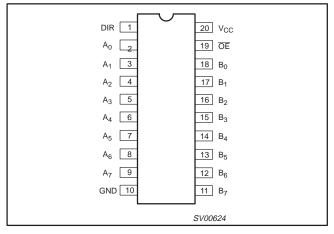
H = HIGH voltage level LOW voltage level L =

don't care

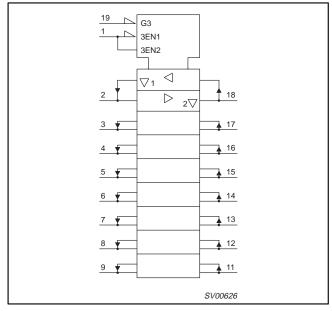
X = Z = high impedance OFF-state

### 74LV245

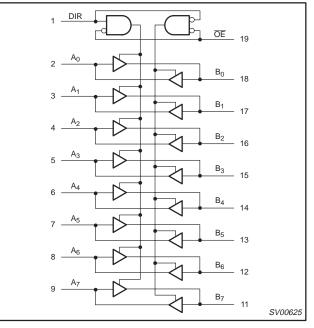
#### **PIN CONFIGURATION**



### LOGIC SYMBOL (IEEE/IEC)



#### LOGIC SYMBOL



### 74LV245

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V <sub>CC</sub>	DC supply voltage	See Note 1	1.0	3.3	5.5	V
VI	Input voltage		0	-	V <sub>CC</sub>	V
Vo	Output voltage		0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$V_{CC} = 1.0V \text{ to } 2.0V \\ V_{CC} = 2.0V \text{ to } 2.7V \\ V_{CC} = 2.7V \text{ to } 3.6V \\ V_{CC} = 3.6V \text{ to } 5.5V$	- - - -	- - - -	500 200 100 50	ns/V

1. The LV is guaranteed to function down to  $V_{CC} = 1.0V$  (input levels GND or  $V_{CC}$ ); DC characteristics are guaranteed from  $V_{CC} = 1.2V$  to  $V_{CC} = 5.5V$ .

### ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
$\pm I_{IK}$	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5 V$	20	mA
$\pm I_{OK}$	DC output diode current	$V_{\rm O}$ < -0.5 or $V_{\rm O}$ > $V_{\rm CC}$ + 0.5V	50	mA
$\pm I_{O}$	DC output source or sink current – bus driver outputs	$-0.5V < V_O < V_{CC} + 0.5V$	35	mA
$^{\pm  I_{GND},}_{\pm  I_{CC}}$	DC V <sub>CC</sub> or GND current for types with – bus driver outputs		70	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
Power dissipation per package – plastic DIL – plastic mini-pack (SO)		for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

					LIMITS	_		
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	o +125°C	דואט 🛛
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	1
		$V_{CC} = 1.2V$	0.9			0.9		
V <sub>IH</sub>	HIGH level Input	$V_{CC} = 2.0 V$	1.4			1.4		
ЧН	voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			2.0		] `
		$V_{CC} = 4.5 \text{ to } 5.5 \text{V}$	0.7 * V <sub>CC</sub>			0.7 * V <sub>CC</sub>		
		$V_{CC} = 1.2V$			0.3		0.3	
VIL	LOW level Input	$V_{CC} = 2.0 V$			0.6		0.6	
۴IL	voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8		0.8	] `
		V <sub>CC</sub> = 4.5 to 5.5			0.3 * V <sub>CC</sub>		0.3 * V <sub>CC</sub>	
		$V_{CC}$ = 1.2V; $V_I$ = $V_{IH}$ or $V_{IL}$ ; $-I_O$ = 100 $\mu$ A		1.2				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	1.8	2.0		1.8		v
V <sub>OH</sub>	HIGH level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	2.5	2.7		2.5		
	·····g-, -···p-···	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	2.8	3.0		2.8		
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	4.3	4.5		4.3		1
	HIGH level output	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 8mA$	2.40	2.82		2.20		v
V <sub>OH</sub>	voltage; BUS driver outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 16mA$	3.60	4.20		3.50		
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	1
V <sub>OL</sub>	LOW level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
	voltage, all outputs	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
V	LOW level output voltage; BUS driver	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 8mA$		0.20	0.40		0.50	v
V <sub>OL</sub>	outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}, I_O = 16mA$		0.35	0.55		0.65	ľ
I <sub>I</sub>	Input leakage current	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}$			1.0		1.0	μΑ
I <sub>OZ</sub>	3-State output OFF-state current	$V_{CC} = 5.5V; V_I = V_{IH} \text{ or } V_{IL;}$ $V_O = V_{CC} \text{ or GND}$			5		10	μΑ
I <sub>CC</sub>	Quiescent supply current; MSI	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		160	μΑ
$\Delta I_{CC}$	Additional quiescent supply current	$V_{CC} = 2.7V$ to 3.6V; $V_{I} = V_{CC} - 0.6V$			500		850	μA

NOTE:

1. All typical values are measured at  $T_{amb} = 25^{\circ}C$ .

## 74LV245

#### **AC CHARACTERISTICS**

GND = 0V;  $t_r = t_f \le 2.5 \text{ns}$ ;  $C_L = 50 \text{pF}$ ;  $R_L = 1 \text{K}\Omega$ 

			CONDITION			LIMITS			
SYMBOL	PARAMETER	WAVEFORM	CONDITION	_	40 to +85 °	°C	-40 to	+125 °C	UNIT
			V <sub>CC</sub> (V)	MIN	TYP <sup>1</sup>	MAX	MIN	MAX	
			1.2		45	28			
tphl/tplh	Propagation delay A <sub>n</sub> to B <sub>n</sub> ; B <sub>n</sub> to A <sub>n</sub>	Figures 1	2.0		15	28		34	
			2.7		11	19		24	ns
		[	3.0 to 3.6		9 <sup>2</sup>	16		20	
			4.5 to 5.5		8 <sup>3</sup>	11		14	
	3-State output enable time $\overline{OE}$ to $A_n$ ;		1.2		55				
		Figures 2	2.0		19	31		39	ns
t <sub>PZH</sub> /t <sub>PZL</sub>			2.7		14	23		29	
	OE to B <sub>n</sub>	[	3.0 to 3.6		10 <sup>2</sup>	18		23	
		[	4.5 to 5.5		8.5 <sup>3</sup>	14		18	
			1.2		65				
	3-State output disable time	[	2.0		24	32		39	
t <sub>PHZ</sub> /t <sub>PLZ</sub>	$\overline{OE}$ to $A_n$ ; $\overline{OE}$ to $B_n$	Figures 2	2.7		18	24		29	ns
	"	[	3.0 to 3.6		14 <sup>2</sup>	20		24	
			4.5 to 5.5		11.5 <sup>3</sup>	16		19	

NOTES:

1. Unless otherwise stated, all typical values are measured at  $T_{amb} = 25^{\circ}C$ 

2. Typical values are measured at V<sub>CC</sub> = 3.3 V.

3. Typical values are measured at  $V_{CC} = 5.0$  V.

#### AC WAVEFORMS

 $\begin{array}{l} \mathsf{V}_M = 1.5 \ \mathsf{V} \ at \ \mathsf{V}_{CC} \geq 2.7 \ \mathsf{V} \ and \leq 3.6 \ \mathsf{V} \\ \mathsf{V}_M = 0.5 \ \mathsf{V} \times \mathsf{V}_{CC} \ at \ \mathsf{V}_{CC} < 2.7 \ \mathsf{V} \ and \geq 4.5 \ \mathsf{V} \\ \mathsf{V}_{OL} \ and \ \mathsf{V}_{OH} \ are \ the \ typical \ output \ voltage \ drop \ that \ occur \ with \ the \ output \ load. \\ \mathsf{V}_X = \mathsf{V}_{OL} + 0.3 \ \mathsf{V} \ at \ \mathsf{V}_{CC} \geq 2.7 \ \mathsf{V} \ and \leq 3.6 \ \mathsf{V} \\ \mathsf{V}_X = \mathsf{V}_{OL} + 0.1 \times \mathsf{V}_{CC} \ at \ \mathsf{V}_{CC} < 2.7 \ \mathsf{V} \ and \geq 4.5 \ \mathsf{V} \\ \mathsf{V}_Y = \mathsf{V}_{OH} - 0.3 \ \mathsf{V} \ at \ \mathsf{V}_{CC} \geq 2.7 \ \mathsf{V} \ and \leq 3.6 \ \mathsf{V} \\ \mathsf{V}_Y = \mathsf{V}_{OH} - 0.1 \times \mathsf{V}_{CC} \ at \ \mathsf{V}_{CC} < 2.7 \ \mathsf{V} \ and \geq 4.5 \ \mathsf{V} \end{array}$ 

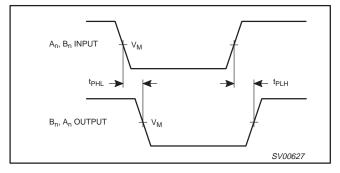


Figure 1. Input  $(A_n, B_n)$  to output  $(B_n, A_n)$  propagation delays and the output transition times.

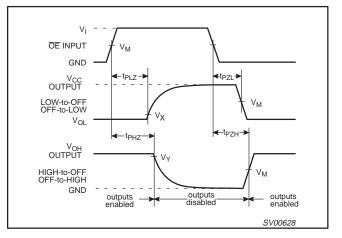


Figure 2. 3-State enable and disable times.

## 74LV245

### **TEST CIRCUIT**

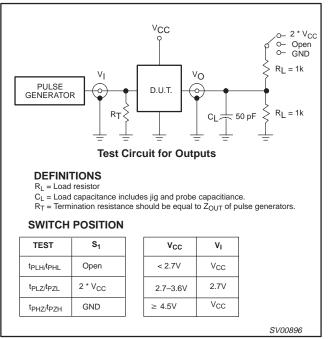


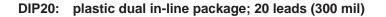
Figure 3. Load circuitry for switching times.

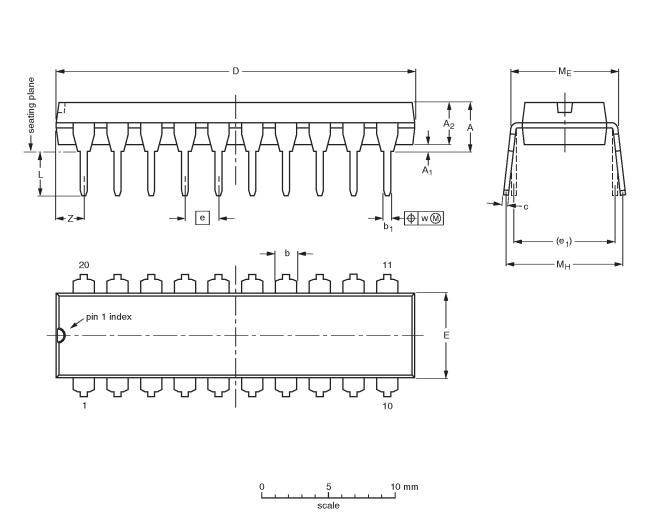
#### Product specification

# Octal bus transceiver (3-State)

## 74LV245

SOT146-1





#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

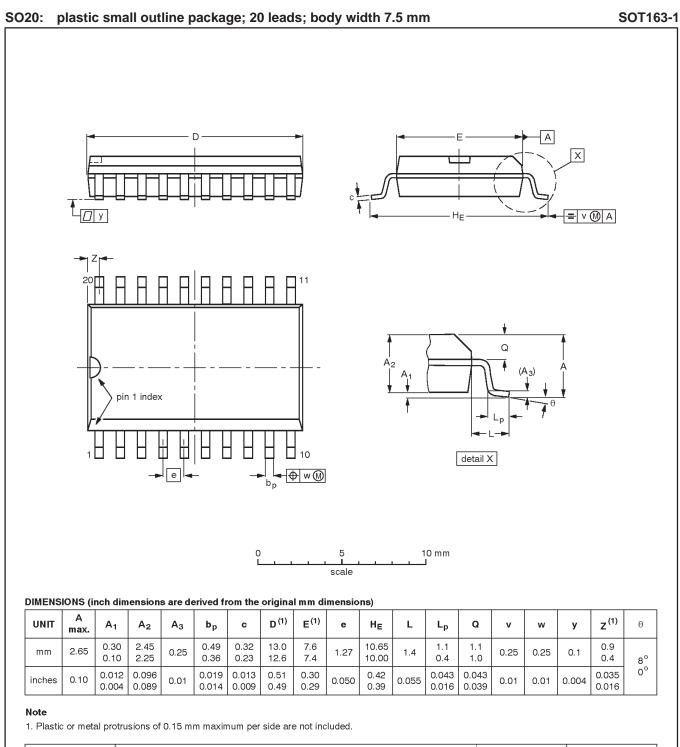
UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	с	D <sup>(1)</sup>	Е <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

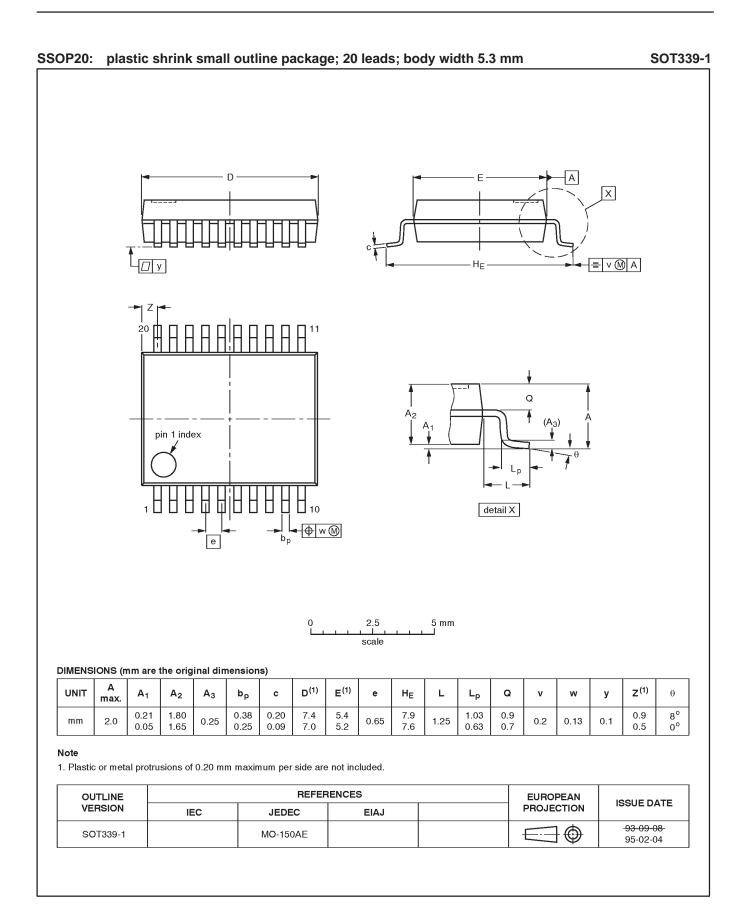
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1			SC603			<del>-92-11-17</del> 95-05-24	

### 74LV245

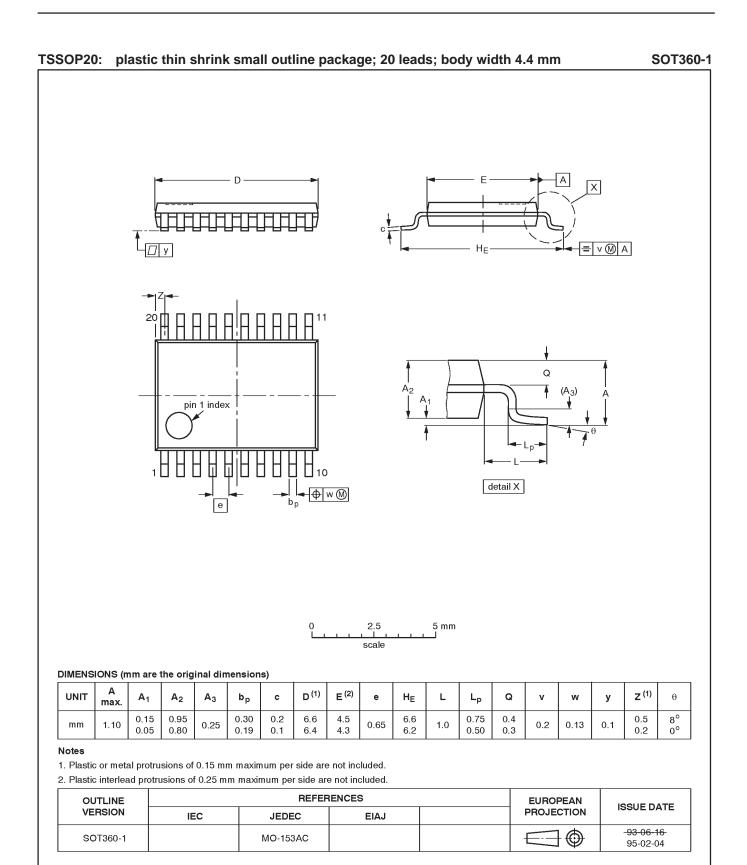


OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>-92-11-17</del> 95-01-24	

74LV245



74LV245



### 74LV245

	DEFINITIONS						
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.					

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print code

Document order number:

Date of release: 05-96 9397-750-04438

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